

U.S. Department of Commerce, Patent and Trademark Office		Atty Docket No.	Application No.
SEP 22 2005		M-12524 US	10/056,154
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Applicant(s)	Confirmation No.
Substitute Form PTO-1449 SEP 22 2005		Fortin, Vincent	2279
		Filing Date	Group
		23 January 2002	2823

U.S. Patent Documents

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
AA							
AB							
AC							
AD							
AE							
AF							
AG							
AH							
AI							
AJ							
AK							
AL							

Foreign Patent Documents

		Document	Date	Country	Class	Subclass	Translation	
	AM							
	AN							
	AO							
	AP							
	AQ							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>Lee</i>	AR	Hopwood, "Ionized physical vapor deposition of integrated circuit interconnects", <u>Physics of Plasmas</u> , May 1998, pp. 1624 - 1631
<i>Lee</i>	AS	"Applied Materials Launches Advanced Cobalt Solution for Nano-Chip Manufacturing", Business Wire, Applied Materials, http://www.businesswire.com/cgi-bin/cnn-storydisplay.cgi?story=www/between/webboc/bw.1204...1 , Dec. 4, 2001, 1 page
	AT	

Examiner *Kris Maysa* Date Considered *11/8/05*

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.